

NLSV4T244E

4-Bit Dual-Supply Non-Inverting Level Translator

The NLSV4T244E is a 4-bit configurable dual-supply voltage level translator. The input A_n and output B_n ports are designed to track two different power supply rails, V_{CCA} and V_{CCB} respectively. Both supply rails are configurable from 0.9 V to 4.5 V allowing universal low-voltage translation from the input A_n to the output B_n port.

Features

- Wide V_{CCA} and V_{CCB} Operating Range: 0.9 V to 4.5 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 4.5 V
- Non-preferential V_{CCA} and V_{CCB} Sequencing
- Outputs at 3-State until Active V_{CC} is Reached
- Power-Off Protection
- Outputs Switch to 3-State with V_{CCB} at GND
- Data Rate > 200 Mbps @ $V_{CCA} = 1.8$ V, $V_{CCB} = 3.3$ V, $R_L = 2$ k Ω , $C_L = 15$ pF
- Ultra-Small Packaging: 1.7 mm x 2.0 mm UQFN12
- These are Pb-Free Devices

Typical Applications

- Mobile Phones, PDAs, Other Portable Devices

Important Information

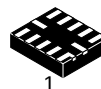
- ESD Protection for All Pins:
 - HBM (Human Body Model) > 2000 V
 - MM (Machine Model) > 400 V



ON Semiconductor®

www.onsemi.com

MARKING DIAGRAMS

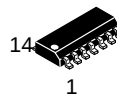


UQFN12
MU SUFFIX
CASE 523AE

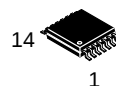
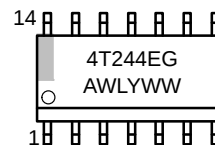


AF = Specific Device Code
M = Date Code
▪ = Pb-Free Package

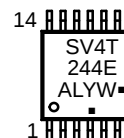
(Note: Microdot may be in either location)



SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or ▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NLSV4T244EMUTAG	UQFN12 (Pb-Free)	3000/Tape & Reel
NLSV4T244EDR2G	SO-14 (Pb-Free)	2500/Tape & Reel
NLSV4T244EDTR2G	TSSOP14 (Pb-Free)	2500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Pin diagram of the 74VHC04 hex inverters. The chip has 14 pins. Pin 1 is VCCA, Pin 2 is A1, Pin 3 is A2, Pin 4 is A3, Pin 5 is A4, Pin 6 is NC, Pin 7 is GND, Pin 8 is B4, Pin 9 is NC, Pin 10 is B3, Pin 11 is B2, Pin 12 is B1, Pin 13 is VCCB, and Pin 14 is OE. The chip has a notch on the left side.



PIN	FUNCTION
V _{CCA}	Input Port DC Power Supply
V _{CCB}	Output Port DC Power Supply
GND	Ground
A _n	Input Port
B _n	Output Port
OE	Output Enable

Inputs		Outputs
$\overline{OE}$	A_n	B_n
L	L	L
L	H	H
H	X	3-State

NLSV4T244E

MAXIMUM RATINGS

Symbol	Rating	Condition	Value	Unit
V_{CCA}, V_{CCB}	DC Supply Voltage		-0.5 to +5.5	V
V_I	DC Input Voltage A_n		-0.5 to +5.5	V
V_C	Control Input $\overline{OE}$		-0.5 to +5.5	V
V_O	DC Output Voltage (Power Down) B_n	$V_{CCA} = V_{CCB} = 0$	-0.5 to +5.5	V
	(Active Mode) B_n		-0.5 to +5.5	V
	(Tri-State Mode) B_n		-0.5 to +5.5	V
I_{IK}	DC Input Diode Current	$V_I < GND$	-20	mA
I_{OK}	DC Output Diode Current	$V_O < GND$	-50	mA
I_O	DC Output Source/Sink Current		±50	mA
I_{CCA}, I_{CCB}	DC Supply Current Per Supply Pin		±100	mA
I_{GND}	DC Ground Current per Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		-65 to +150	°C
T_J	Junction Temperature		+125	°C
θ_{JA}	Junction-to-Ambient Thermal Resistance		53	°C/W
$\Psi_{JC(top)}$	Junction-to-Case (Top) Thermal Resistance		10	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CCA}, V_{CCB}	Positive DC Supply Voltage	0.9	4.5	V
V_I	Bus Input Voltage	GND	4.5	V
V_C	Control Input $\overline{OE}$	GND	4.5	V
V_{IO}	Bus Output Voltage (Power Down Mode) B_n	GND	4.5	V
	(Active Mode) B_n	GND	V_{CCB}	V
	(Tri-State Mode) B_n	GND	4.5	V
T_A	Operating Temperature Range	-40	+85	°C
$\Delta t / \Delta V$	Input Transition Rise or Rate V_I , from 30% to 70% of V_{CC} ; $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	nS

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NLSV4T244E

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CCA} (V)	V _{CCB} (V)	-40°C to +85°C		Unit
					Min	Max	
V _{IH}	Input HIGH Voltage (An, OE)		3.6 – 4.5	0.9 – 4.5	2.2	–	V
			2.7 – 3.6		2.0	–	
			2.3 – 2.7		1.6	–	
			1.4 – 2.3		0.65 * V _{CCA}	–	
			0.9 – 1.4		0.9 * V _{CCA}	–	
V _{IL}	Input LOW Voltage (An, OE)		3.6 – 4.5	0.9 – 4.5	–	0.8	V
			2.7 – 3.6		–	0.8	
			2.3 – 2.7		–	0.7	
			1.4 – 2.3		–	0.35 * V _{CCA}	
			0.9 – 1.4		–	0.1 * V _{CCA}	
V _{OH}	Output HIGH Voltage	I _{OH} = -100 µA; V _I = V _{IH}	0.9 – 4.5	0.9 – 4.5	V _{CCB} - 0.2	–	V
		I _{OH} = -0.5 mA; V _I = V _{IH}	0.9	0.9	0.75 * V _{CCB}	–	
		I _{OH} = -2 mA; V _I = V _{IH}	1.4	1.4	1.05	–	
		I _{OH} = -6 mA; V _I = V _{IH}	1.65	1.65	1.25	–	
			2.3	2.3	2.0	–	
		I _{OH} = -12 mA; V _I = V _{IH}	2.3	2.3	1.8	–	
			2.7	2.7	2.2	–	
		I _{OH} = -18 mA; V _I = V _{IH}	2.3	2.3	1.7	–	
			3.0	3.0	2.4	–	
V _{OL}	Output LOW Voltage	I _{OL} = 100 µA; V _I = V _{IL}	0.9 – 4.5	0.9 – 4.5	–	0.2	V
		I _{OL} = 0.5 mA; V _I = V _{IH}	1.1	1.1	–	0.3	
		I _{OL} = 2 mA; V _I = V _{IH}	1.4	1.4	–	0.35	
		I _{OL} = 6 mA; V _I = V _{IL}	1.65	1.65	–	0.3	
		I _{OL} = 12 mA; V _I = V _{IL}	2.3	2.3	–	0.4	
			2.7	2.7	–	0.4	
		I _{OL} = 18 mA; V _I = V _{IL}	2.3	2.3	–	0.6	
			3.0	3.0	–	0.45	
		I _{OL} = 24 mA; V _I = V _{IL}	3.0	3.0	–	0.6	
I _I	Input Leakage Current	V _I = V _{CCA} or GND	0.9 – 4.5	0.9 – 4.5	-1.0	1.0	µA
I _{OFF}	Power-Off Leakage Current	OE = 0 V	0 0.9 – 4.5	0.9 – 4.5 0	-1.0 -1.0	1.0 1.0	µA
I _{CCA}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	µA
I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	2.0	µA
I _{CCA} + I _{CCB}	Quiescent Supply Current	V _I = V _{CCA} or GND; I _O = 0, V _{CCA} = V _{CCB}	0.9 – 4.5	0.9 – 4.5	–	4.0	µA
ΔI _{CCA}	Increase in I _{CC} per Input Voltage, Other Inputs at V _{CCA} or GND	V _I = V _{CCA} - 0.6 V; V _I = V _{CCA} or GND	4.5 3.6	4.5 3.6	–	10 5.0	µA
ΔI _{CCB}	Increase in I _{CC} per Input Voltage, Other Inputs at V _{CCA} or GND	V _I = V _{CCA} - 0.6 V; V _I = V _{CCA} or GND	4.5 3.6	4.5 3.6	–	10 5.0	µA
I _{OZ}	I/O Tri-State Output Leakage Current	T _A = 25°C, OE = 0V _{CCA} , V _O = 0 to V _{CCB} + 0.5 V	0.9 – 4.5	0.9 – 4.5	–	1.0	µA
		T _A = 25°C, OE = 0V _{CCA} , V _O = 0 to 4.5 V			–	75	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NLSV4T244E

TOTAL STATIC POWER CONSUMPTION ($I_{CCA} + I_{CCB}$)

V _{CCA} (V)	-40°C to +85°C										Unit
	V _{CCB} (V)										
	4.5		3.3		2.8		1.8		0.9		
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
4.5		2		2		2		2		< 1.5	μA
3.3		2		2		2		2		< 1.5	μA
2.8		< 2		< 1		< 1		< 0.5		< 0.5	μA
1.8		< 1		< 1		< 0.5		< 0.5		< 0.5	μA
0.9		< 0.5		< 0.5		< 0.5		< 0.5		< 0.5	μA

NOTE: Connect ground before applying supply voltage V_{CCA} or V_{CCB} . This device is designed with the feature that the power-up sequence of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CCA} (V)	−40°C to +85°C										Unit
			V _{CCB} (V)										
			4.5		3.3		2.8		1.8		1.5		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL} (Note 1)	Propagation Delay, A _n to B _n	4.5		3.0		3.2		3.4		3.7		4.0	nS
		3.6		3.3		3.5		3.7		4.0		4.3	
		2.8		3.5		3.7		3.9		4.2		4.5	
		1.8		3.8		4.0		4.2		4.5		4.8	
		1.5		4.1		4.3		4.5		4.8		5.0	
t _{PZH} , t _{PZL} (Note 1)	Output Enable, OE to B _n	4.5		4.4		4.8		5.2		5.7		6.2	nS
		3.3		4.7		5.1		5.5		6.0		6.5	
		2.8		4.9		5.3		5.7		6.2		6.7	
		1.8		5.2		5.6		6.0		6.5		7.0	
		1.5		5.5		5.9		6.3		6.8		7.3	
t _{PHZ} , t _{PLZ} (Note 1)	Output Disable, OE to B _n	4.5		4.4		4.8		5.2		5.7		6.2	nS
		3.3		4.7		5.1		5.5		6.0		6.5	
		2.8		4.9		5.3		5.7		6.2		6.7	
		1.8		5.2		5.6		6.0		6.5		7.0	
		1.5		5.5		5.9		6.3		6.8		7.3	
t _{OSHL} , t _{OSLH} (Note 1)	Output to Output Skew, Data to Out-put	4.1		0.15		0.15		0.15		0.15		0.15	nS
		3.6		0.15		0.15		0.15		0.15		0.15	
		2.8		0.15		0.15		0.15		0.15		0.15	
		1.8		0.15		0.15		0.15		0.15		0.15	
		1.2		0.15		0.15		0.15		0.15		0.15	

1. Propagation delays defined per Figures 3 and 4.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
C_{IN}	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or $V_{CCA/B}$	3.5	pF
$C_{I/O}$	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or $V_{CCA/B}$	5.0	pF
C_{PD}	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3$ V, $V_I = 0$ V or V_{CCA} , $f = 10$ MHz	20	pF

2. Typical values are at $T_A = +25^\circ C$.

3. C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from:

$$I_{CC(operating)} \approx C_{PD} \times V_{CC} \times f_{IN} \times N_{SW} \text{ where } I_{CC} = I_{CCA} + I_{CCB} \text{ and } N_{SW} = \text{total number of outputs switching.}$$

NLSV4T244E

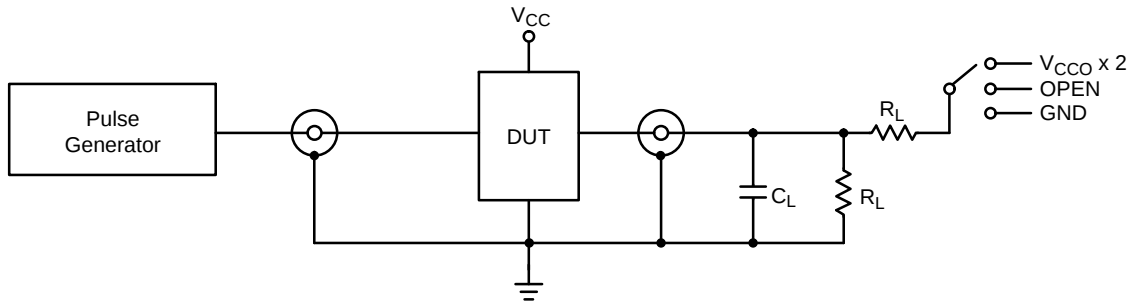
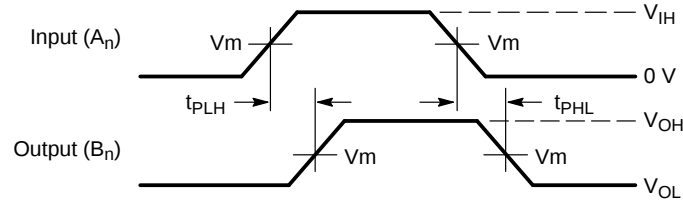


Figure 3. AC (Propagation Delay) Test Circuit

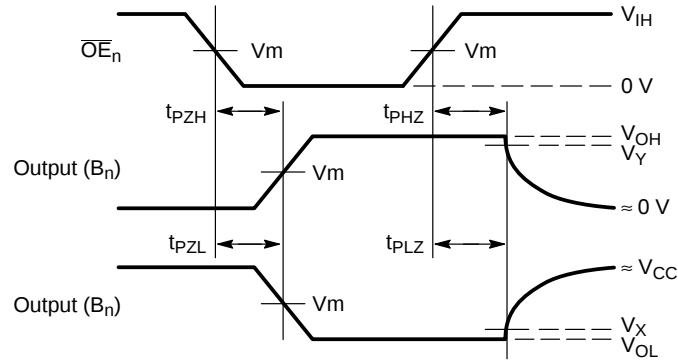
Test	Switch
t_{PLH} , t_{PHL}	OPEN
t_{PLZ} , t_{PZL}	$V_{CCO} \times 2$
t_{PHZ} , t_{PZH}	GND

$C_L = 15 \text{ pF}$ or equivalent (includes probe and jig capacitance)
 $R_L = 2 \text{ k}\Omega$ or equivalent
 Z_{OUT} of pulse generator = 50Ω



Waveform 1 – Propagation Delays

$t_R = t_F = 2.0 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$



Waveform 2 – Output Enable and Disable Times

$t_R = t_F = 2.0 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$

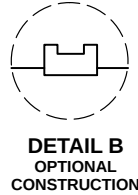
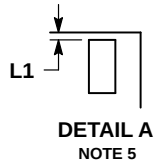
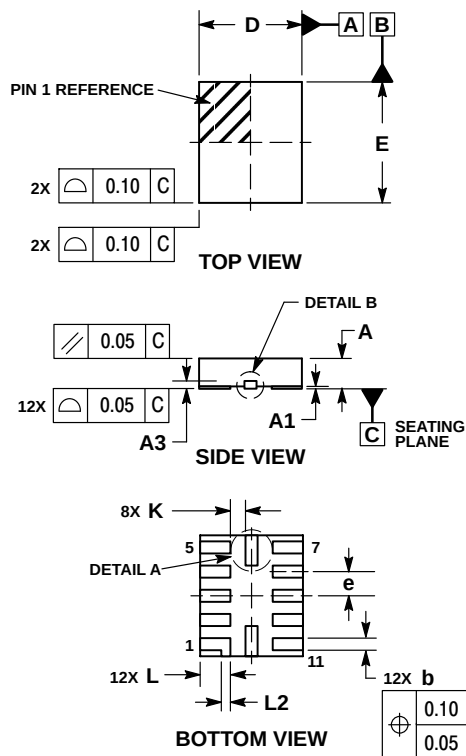
Figure 4. AC (Propagation Delay) Test Circuit Waveforms

Symbol	V_{CC}				
	3.0 V – 4.5 V	2.3 V – 2.7 V	1.65 V – 1.95 V	1.4 V – 1.6 V	0.9 V – 1.3 V
V_{mA}	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$	$V_{CCA}/2$
V_{mB}	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$	$V_{CCB}/2$
V_X	$V_{OL} \times 0.1$	$V_{OL} \times 0.1$	$V_{OL} \times 0.1$	$V_{OL} \times 0.1$	$V_{OL} \times 0.1$
V_Y	$V_{OH} \times 0.9$	$V_{OH} \times 0.9$	$V_{OH} \times 0.9$	$V_{OH} \times 0.9$	$V_{OH} \times 0.9$

NLSV4T244E

PACKAGE DIMENSIONS

UQFN12 1.7x2.0, 0.4P
CASE 523AE
ISSUE A

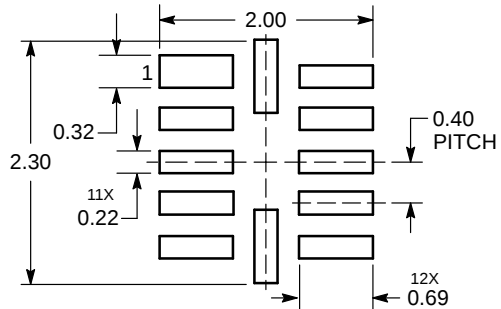


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH 0.03 MAX ON BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.70 BSC	
E	2.00 BSC	
e	0.40 BSC	
K	0.20	----
L	0.45	0.55
L1	0.00	0.03
L2	0.15 REF	

MOUNTING FOOTPRINT SOLDERMASK DEFINED



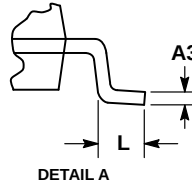
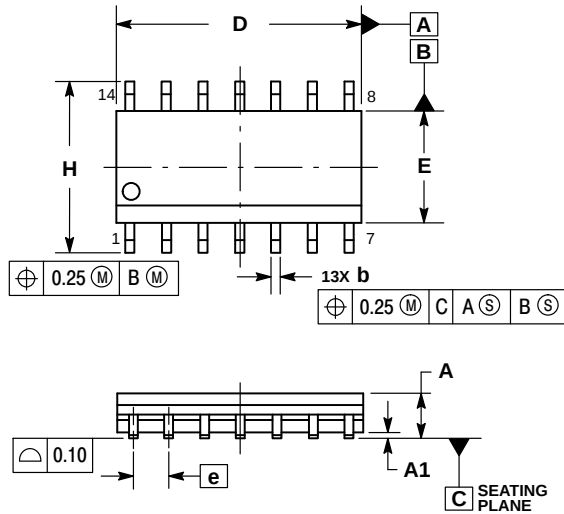
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NLSV4T244E

PACKAGE DIMENSIONS

SOIC-14
D SUFFIX
CASE 751A-03
ISSUE L

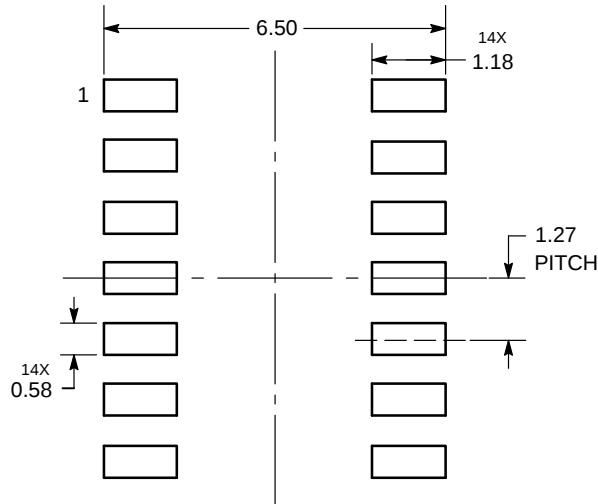


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC	0.050 BSC		
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

